# MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PLED

NUP1105LT1G-MS

### **Product specification**



## NUP1105LT1G-MS

# **MSKSEMI**

#### **Features**

- 350 Watts peak pulse power (tp = 8/20µs)
- Unidirectional and unidirecti onal configurations
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- IEC 61000-4-2 ±20kV contact ±20kV air
- IEC 61000-4-4 (EFT) 40A (5 /50ns)
- IEC 61000-4-5 (Lightning) 8A (8/20µs)

#### Application

- Dataline
- Automatic Teller Machines
- Net works
- Power line

#### **Mechanical Data**

SOT-23 package

Molding compound flammability rating: UL 94V-0 Packaging: Tape and Reel RoHS/WEEE Compliant

#### **Reference News**

PACKAGE OUTLINE	Pin Configuration	Marking
SOT-23	- Z	27 <b>片</b> *



#### Absolute Maximum Rating

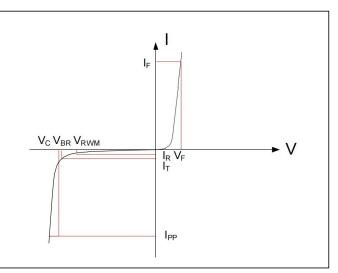
Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p=8/20\mu s$ )	P <sub>PP</sub>	350	Watts
Peak Pulse Current ( $t_p=8/20\mu s$ ) (note1)	$I_{pp}$	8	А
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V <sub>ESD</sub>	20 20	kV
Lead Soldering Temperature	T <sub>L</sub>	260(10seconds)	°C
Junction Temperature	TJ	-55 to + 125	°C
Storage Temperature	T <sub>stg</sub>	-55 to + 125	°C

#### **Electrical Characteristics**

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V <sub>RWM</sub>		24		26	V
Reverse Breakdown Voltage	$V_{BR}$	I <sub>T</sub> =1mA	25			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> =24V,T=25C			1.0	μΑ
Peak Pulse Current	I <sub>PP</sub>	tp =8/20µs			8	А
Clamping Voltage	Vc	$I_{PP}=8A, t_p=8/20 \mu s$		44		V
Junction Capacitance	Cj	$V_R = 0V, f = 1MHz$ (Pin 1 to Pin 2)		30		pF

#### **Electrical Parameters (TA = 25°C unless otherwise noted)**

Symbol	Parameter		
РР	Maximum Reverse Peak Pulse Current		
С	Clamping Voltage @ IPP		
RWM	Working Peak Reverse Voltage		
R	Maximum Reverse Leakage Current @ VRWM		
BR	Breakdown Voltage @ IT		
Т	Test Current		



Note:. 8/20µs pulse waveform

#### MSKSEMI SEMICONDUCTOR

#### **Typical Characteristics**

Figure 1: Peak Pulse Power vs. Pulse Time

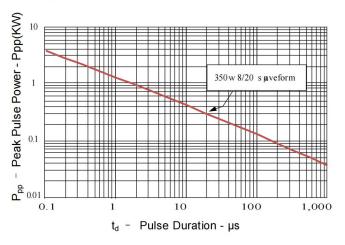


Figure 2: Power Derating Curve

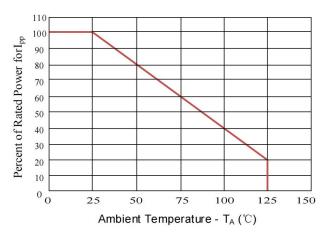


Figure3: Pulse Waveform

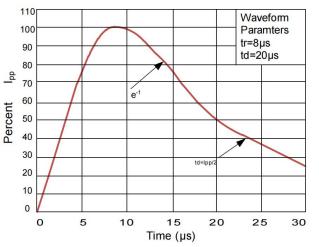


Figure 5: Peak Pulse Power Vs Junction Temperature

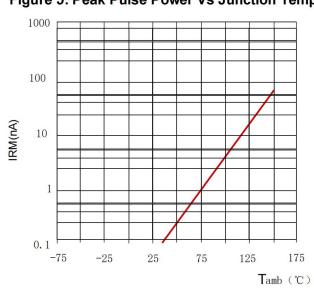
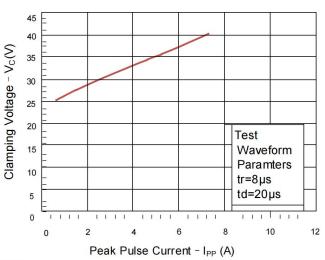
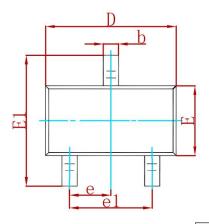


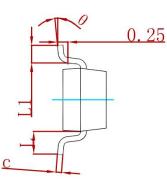
Figure 4: Clamping Voltage vs.lpp

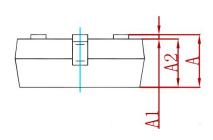




#### PACKAGE MECHANICAL DATA

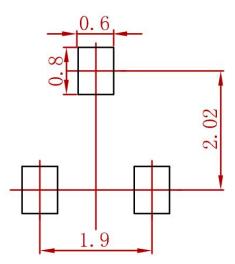






Symbol	<b>Dimensions In Millimeters</b>		Dimensions In Inches	
Symbol	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
С	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
е	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

#### **Suggested Pad Layout**



Note:

1.Controlling dimension: in millimeters.

2.General tolerance:±0.05mm.

3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
NUP1105LT1G-MS	SOT-23	3000



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